

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. (Currently Amended) A laminate comprising two or more magnetic metal thin plates, each magnetic metal thin plate being selected from the group consisting of an amorphous metal plate~~[],]~~ and a nano crystal magnetic plate and a silicon steel sheet and coated with a high molecular compound, wherein the two or more magnetic metal thin plates are partially in contact with one another via the high molecular compound, and wherein the volume resistivity defined in JIS H 0505 in a direction perpendicular to the high molecular compound surface of the magnetic metal thin plates is from 0.1 Ωcm to less than 10⁸ Ωcm.

2. (Previously Presented) The laminate according to claim 1, wherein the high molecular compound layer covers not less than 50% of the area of the two or more magnetic metal thin plates, and the volume resistivity defined in JIS H 0505 in a direction perpendicular to the high molecular compound surface of the two or more magnetic metal thin plates is from 1 Ωcm to less than 10⁶ Ωcm.

3. (Previously Presented) The laminate according to claim 1, wherein two or more kinds of magnetic metal thin plates are used as the two or more magnetic metal thin plates.

4. (Canceled)

5. (Previously Presented) The laminate according to claim 3, wherein the two or more magnetic metal thin plates include an amorphous metal plate and a silicon steel sheet.

6. (Withdrawn/ Previously Presented) A method of manufacturing the laminate according to claim 1, comprising:

stacking two or more magnetic metal thin plates coated with a high molecular compound; and

applying pressure of from 0.2 to 100 MPa to the two or more magnetic metal thin plates such that the two or more magnetic thin plates are partially in contact with one another via the high molecular compound.

7. (Withdrawn/ Previously Presented) A method of manufacturing the laminate according to claim 1, comprising:

coating not less than 50% of the area of the two or more magnetic metal thin plates with a high molecular compound and drying

punching the two or more magnetic metal thin plates obtained;

stacking them and subjecting them to plastic deformation; and

heating the resulting two or more magnetic metal thin plates while applying pressure of from 0.2 to 100 MPa thereto to form an integrated laminate.

8. (Withdrawn/ Previously Presented) The method according to claim 7, wherein the method of subjecting to plastic deformation is a caulking process.

9. (Previously Presented) The laminate according to claim 3, wherein the laminate is used for any of a transformer, an inductor and an antenna.

10. (Previously Presented) The laminate according to claim 3, wherein the laminate is used for a magnetic core material of a stator or a rotor of a motor or a generator.

11. (Previously Presented) The laminate according to claim 1, wherein the laminate is used for any of a transformer, an inductor and an antenna.

12. (Previously Presented) The laminate according to claim 1, wherein the laminate is used for a magnetic core material of a stator or a rotor of a motor or a generator.

13. (Previously Presented) The laminate according to claim 1, wherein the high molecular compound is selected from the group consisting of a polyimide resin, a silicon-containing resin, a ketone resin, a polyamide resin, a liquid crystal polymer, a nitrile resin, a thioether resin, a polyester resin, an arylate resin, a sulfone resin, an imide resin, and an amide-imide resin.

14. (Previously Presented) The laminate according to claim 1, wherein the high molecular compound is selected from the group consisting of a polyimide resin, a sulfone resin, and an amide-imide resin.

15. (New) A laminate comprising two or more magnetic metal thin plates, each magnetic metal thin plate being selected from the group consisting of a nano crystal magnetic plate and a silicon steel sheet and coated with a high molecular compound, wherein the two or more magnetic metal thin plates are partially in contact with one another via the high molecular compound, and wherein the volume resistivity defined in JIS H 0505 in a direction perpendicular to the high molecular compound surface of the magnetic metal thin plates is from 0.1 Ωcm to less than 10^8 Ωcm.

16. (New) The laminate according to claim 15, wherein the high molecular compound layer covers not less than 50% of the area of the two or more magnetic metal thin plates, and the volume resistivity defined in JIS H 0505 in a direction perpendicular to the high molecular compound surface of the two or more magnetic metal thin plates is from 1 Ωcm to less than 10^6 Ωcm.